Abstracts

Development of an organic wafer-level packaging platform for highly integrated RF transceivers

R. Ramachandran and A. Pham. "Development of an organic wafer-level packaging platform for highly integrated RF transceivers." 2002 MTT-S International Microwave Symposium Digest 02.3 (2002 Vol. III [MWSYM]): 1401-1404 vol.3.

We present the development of a novel organic-micromachined packaging scheme at the wafer level for highly integrated RF transceivers. This process enables the integration of on-chip passive devices and isolation structures at the wafer level. We demonstrate the development of inductors that achieve a Q-factor of about 61 at 1.7 GHz and on-chip isolation structures that provide an isolation of more than 50 dB in the GHz range.

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